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EM256L16 Family

256Kx16 bit Ultra-Low Power Asynchronous Static RAM

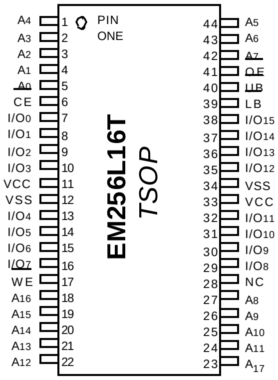
Overview

The EM256L16 is a integrated memory device containing a low power 4 Mbit Static Random Access Memory organized as 262,144 words by 16 bits. The base design is the same as NanoAmp's EM256U16 which is processed to operate at lower voltages. The device is fabricated using NanoAmp's advanced CMOS process and high-speed/ ultra low-power/low-voltage circuit technology. The device pinout is compatible with other standard 256K x 16 SRAMs.

Features

- **Wide Voltage Range:**
  2.3 to 3.6 Volts
- **Extended Temperature Range:**
  -40 to +85 ^{o}C
- **Fast Cycle Time:**
  T_{ACC} < 70 nS @ 2.7V
- **Very Low Operating Current:**
  I_{CC} < 10 mA typical at 3V, 10 Mhz
- **Very Low Standby Current:**
  I_{SB} < 10 µA @ 55 ^{o}C
- **44-Pin TSOP, 48-Pin BGA Available**

FIGURE 1: Pin Configuration



	1	2	3	4	5	6
A	$\overline{LB}$	$\overline{OE}$	A_0	A_1	A_2	NC
B	I/O_8	$\overline{UB}$	A_3	A_4	$\overline{CE}$	I/O_0
C	I/O_9	I/O_{10}	A_5	A_6	I/O_1	I/O_2
D	V_{SS}	I/O_{11}	A_{17}	A_7	I/O_3	V_{CC}
E	V_{CC}	I/O_{12}	NC	A_{16}	I/O_4	V_{SS}
F	I/O_{14}	I/O_{13}	A_{14}	A_{15}	I/O_5	I/O_6
G	I/O_{15}	NC	A_{12}	A_{13}	$\overline{WE}$	I/O_7
H	NC	A_8	A_9	A_{10}	A_{11}	NC

48 Pin BGA (top)
6 x 8 mm

TABLE 1: Pin Descriptions

Pin Name	Pin Function
A_0-A_{17}	Address Inputs
$\overline{WE}$	Write Enable Input
$\overline{CE}$	Chip Enable Input
$\overline{OE}$	Output Enable Input
$\overline{UB}$	Upper Byte Enable Input
$\overline{LB}$	Lower Byte Enable Input
I/O_0-I/O_{15}	Data Inputs/Outputs
V_{CC}	Power
V_{SS}	Ground
NC	Not Connected

FIGURE 1: Typical Operating Current Curves

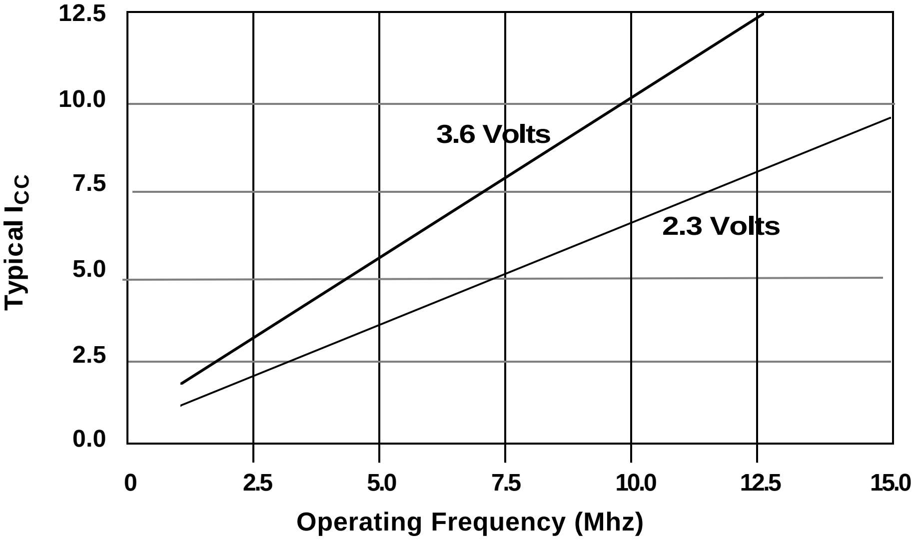


FIGURE 3: Functional Block Diagram

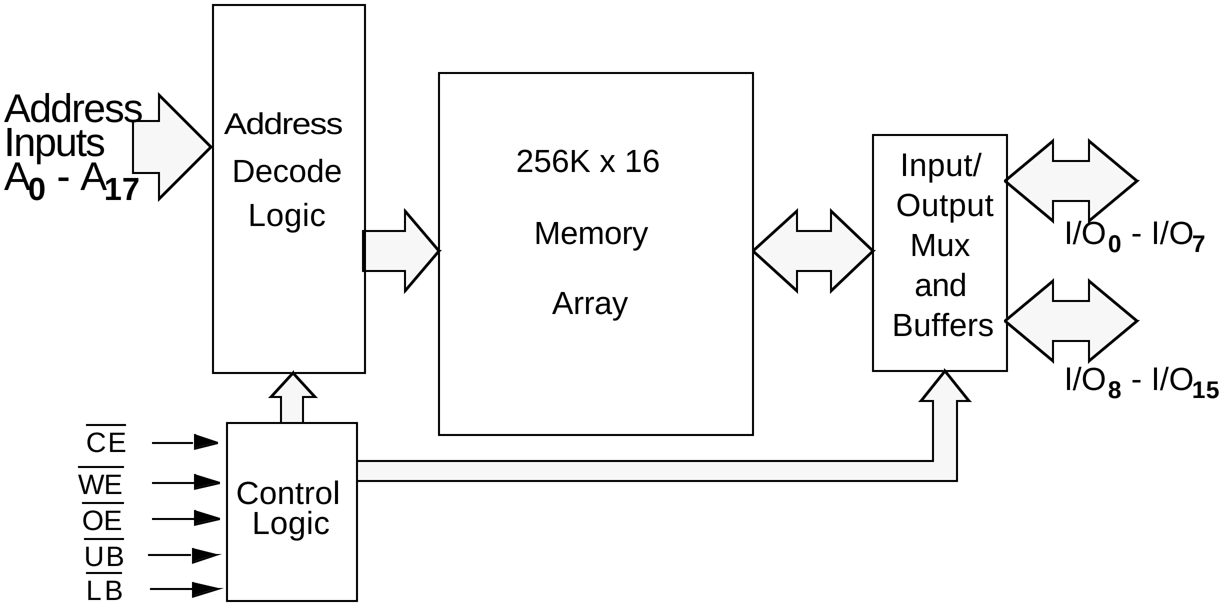


TABLE 2: Functional Description

$\overline{CE}$	$\overline{WE}$	$\overline{OE}$	$\overline{UB}$	$\overline{LB}$	I/O_0 - I/O_{15} [1]	MODE	POWER
H	X	X	X	X	High Z	Standby[2]	Standby
X	X	X	H	H	High Z	Standby[2]	Standby
L	L	X[3]	L[1]	L[1]	Data In	Write[3]	Active
L	H	L	L[1]	L[1]	Data Out	Read	Active
L	H	H	L[1]	L[1]	High Z	Active	Standby[4]

1. When $\overline{UB}$ and $\overline{LB}$ are in select mode (low), I/O_0 - I/O_{15} are affected as shown. When $\overline{LB}$ only is in the select mode only I/O_0 - IO_7 are affected as shown. When $\overline{UB}$ is in the select mode only I/O_8 - I/O_{15} are affected as shown. If both $\overline{UB}$ and $\overline{LB}$ are in the deselect mode (high), the chip is in a standby mode regardless of the state of $\overline{CE}$.
2. When the device is in standby mode, control inputs ($\overline{WE}$, $\overline{OE}$, $\overline{UB}$, and $\overline{LB}$), address inputs and data input/outputs are internally isolated from any external influence and disabled from exerting any influence externally.
3. When $\overline{WE}$ is invoked, the $\overline{OE}$ input is internally disabled and has no effect on the circuit.
4. The device will consume active power in this mode whenever addresses are changed. Data inputs are internally isolated from any external influence.

TABLE 3: Capacitance*

Item	Symbol	Test Condition	Min	Max	Unit
Input Capacitance	C_{IN}	V_{IN} = 0V, f = 1 MHz, T_A = 25°C		8	pF
I/O Capacitance	$C_{I/O}$	V_{IN} = 0V, f = 1 MHz, T_A = 25°C		8	pF

Note: These parameters are verified in device characterization and are not 100% tested

TABLE 4: Absolute Maximum Ratings*

Item	Symbol	Rating	Unit
Voltage on any pin relative to V_{SS}	$V_{IN,OUT}$	–0.3 to V_{CC}+0.3	V
Voltage on V_{CC} Supply Relative to V_{SS}	V_{CC}	–0.3 to 5.0	V
Power Dissipation	P_D	500	mW
Storage Temperature	T_{STG}	–40 to 125	^oC
Operating Temperature	T_A	-40 to +85	^oC
Soldering Temperature and Time	T_{SOLDER}	260 ^{o}C, 10sec(Lead only)	^oC

* Stresses greater than those listed above may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operating section of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

TABLE 5: Operating Characteristics (Over specified Temperature Range)

Item	Symbol	Test Conditions	Min	Typ	Max	Unit
Supply Voltage	V_{CC}		2.3		3.6	V
Data Retention Voltage	V_{DR}	Chip Disabled (Note 3)	1.8			V
Input High Voltage	V_{IH}		0.7V_{CC}		V_{CC}+0.5	V
Input Low Voltage	V_{IL}		–0.5		0.3V_{CC}	V
Output High Voltage	V_{OH}	I_{OH} = 0.2mA	V_{CC}–0.2			V
Output Low Voltage	V_{OL}	I_{OL} = -0.2mA			0.2	V
Input Leakage Current	I_{LI}	V_{IN} = 0 to V_{CC}			0.5	µA
Output Leakage Current	I_{LO}	$\overline{OE}$ = V_{IH} or Chip Disabled			0.5	µA
Read/Write Operating Supply Current @ 1 µS Cycle Time (Note 1)	I_{CC1}	VCC=3.6 V, V_{IN}=V_{IH} or V_{IL} Chip Enabled, IOL = 0			3.0	mA
Read/Write Operating Supply Current @ 70 nS Cycle Time (Note 1)	I_{CC2}	VCC=3.6 V, V_{IN}=V_{IH} or V_{IL} Chip Enabled, IOL = 0			14.0	mA
Operating Standby Current (Note 2)	I_{SB1}	V_{IN} = V_{CC} or 0V Chip Disabled t_A= 55^{o}C, VCC = 3.3V			10	µA
Maximum Standby Current (Note 2)	I_{SB2}	V_{IN} = V_{CC} or 0V Chip Disabled t_A= 85^{o}C, VCC = 3.3V			20	µA
Maximum Data Retention Current (Note 2)	I_{DR}	Vcc = 2.0V, V_{IN} = V_{CC} or 0 Chip Disabled, t_A= 85^{o}C			10	µA

1. This parameter is specified with the outputs disabled to avoid external loading effects. The user must add current required to drive output capacitance expected in the actual system.
2. This device assumes a standby mode if the chip is disabled ($\overline{CE}$ high or $\overline{UB}$ and $\overline{LB}$ high). In order to achieve low standby current all inputs must be within 0.2 volts of either VCC or VSS.
3. The Chip is Disabled when $\overline{CE}$ is high or when both $\overline{UB}$ and $\overline{LB}$ are high. The Chip is Enabled when $\overline{CE}$ is low and $\overline{UB}$ or $\overline{LB}$ is low.

TABLE 6: Timing Test Conditions

Item	
Input Pulse Level	$0.1V_{CC}$ to $0.9\ V_{CC}$
Input Rise and Fall Time	5ns
Input and Output Timing Reference Levels	$0.5\ V_{CC}$
Output Load	CL = 30pF
Operating Temperature	-40 to +85°C

TABLE 7: Timing

Item	Symbol	2.3 - 3.6 V		2.7 - 3.6 V		Units
		Min.	Max.	Min.	Max.	
Read Cycle Time	t_{RC}	85		70		ns
Address Access Time	t_{AA}		85		70	ns
Chip Enable to Valid Output	t_{CO}		85		70	ns
Output Enable to Valid Output	t_{OE}		30		25	ns
Byte Select to Valid Output	t_{LB}, t_{UB}		85		70	ns
Chip Enable to Low-Z output	t_{LZ}	10		10		ns
Output Enable to Low-Z Output	t_{OLZ}	5		5		ns
Byte Select to Low-Z Output	t_{LBZ}, t_{UBZ}	10		10		ns
Chip Disable to High-Z Output	t_{HZ}	0	20	0	20	ns
Output Disable to High-Z Output	t_{OHZ}	0	20	0	20	ns
Byte Select Disable to High-Z Output	t_{LBHZ}, t_{UBHZ}	0	20	0	20	ns
Output Hold from Address Change	t_{OH}	10		10		ns
Write Cycle Time	t_{WC}	85		70		ns
Chip Enable to End of Write	t_{CW}	50		50		ns
Address Valid to End of Write	t_{AW}	50		50		ns
Byte Select to End of Write	t_{LBW}, t_{UBW}	50		50		ns
Write Pulse Width	t_{WP}	40		40		ns
Address Setup Time	t_{AS}	0		0		ns
Write Recovery Time	t_{WR}	0		0		ns
Write to High-Z Output	t_{WHZ}		20		20	ns
Data to Write Time Overlap	t_{DW}	40		40		ns
Data Hold from Write Time	t_{DH}	0		0		ns
End Write to Low-Z Output	t_{OW}	5		5		ns

FIGURE 4: Timing of Read Cycle (1) ($\overline{CE}$ = $\overline{OE}$ = V_{IL}, $\overline{WE}$ = V_{IH})

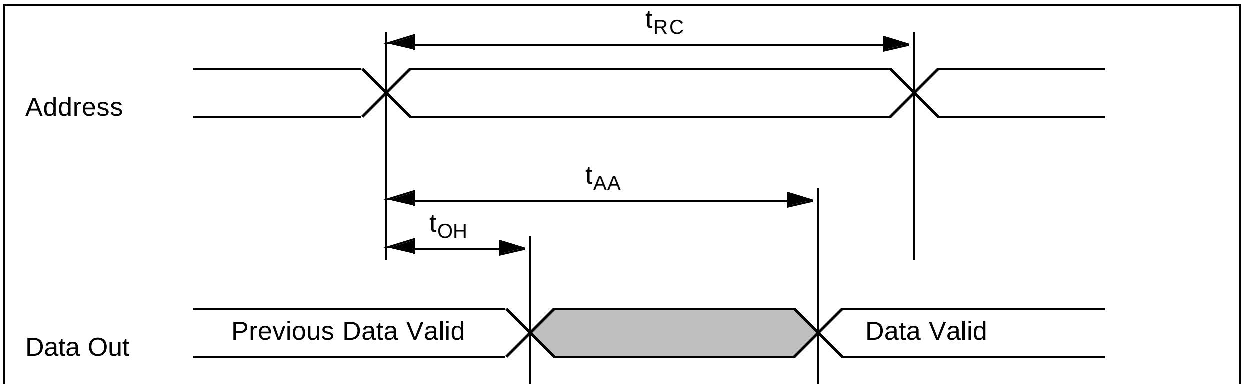


FIGURE 5: Timing Waveform of Read Cycle (2) ($\overline{WE}$ = V_{IH})

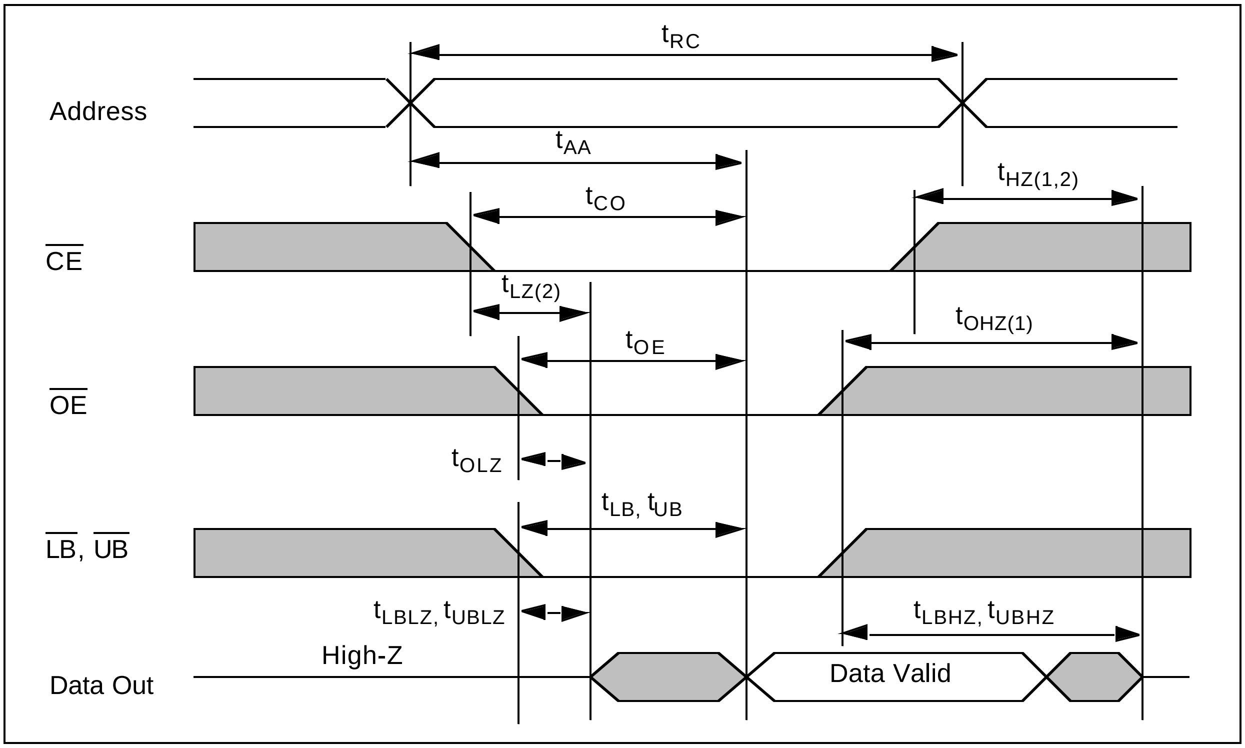


FIGURE 6: Timing Waveform of Write Cycle (1) ($\overline{\text{WE}}$ control)

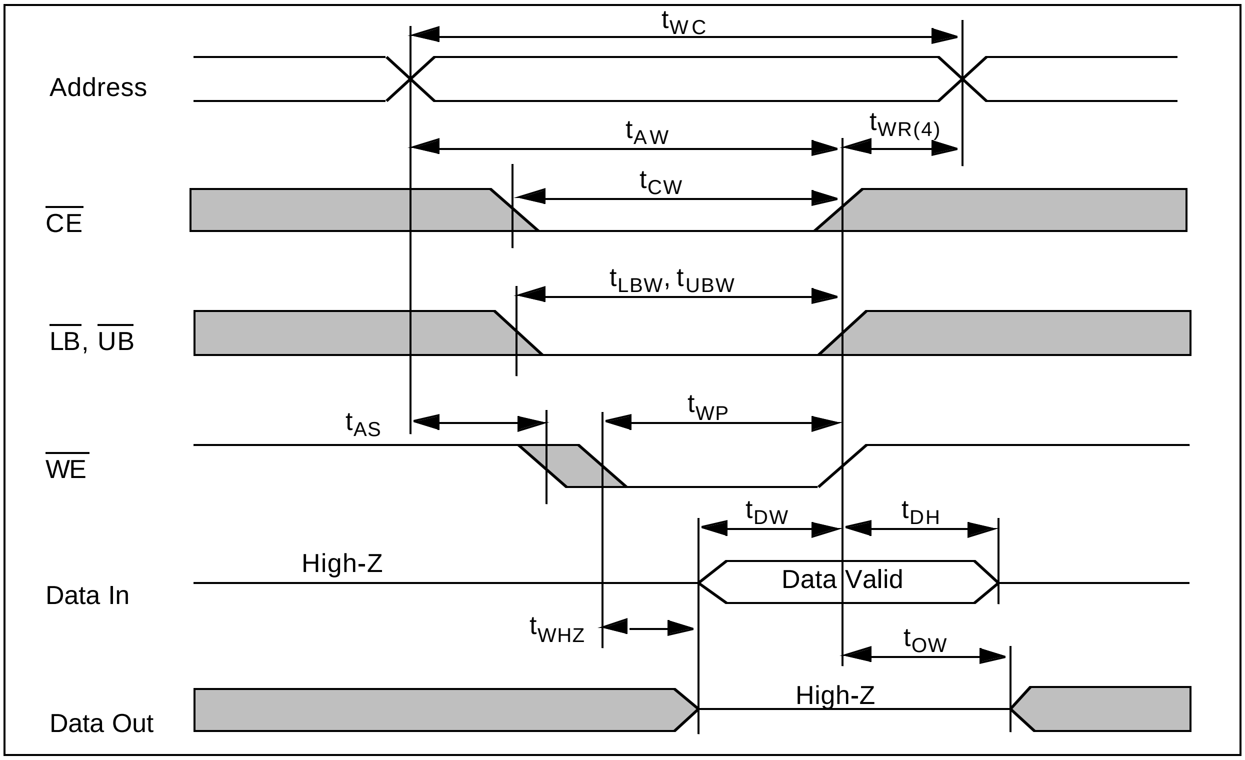


FIGURE 7: Timing Waveform of Write Cycle (2) ($\overline{\text{CE}}$ Control)

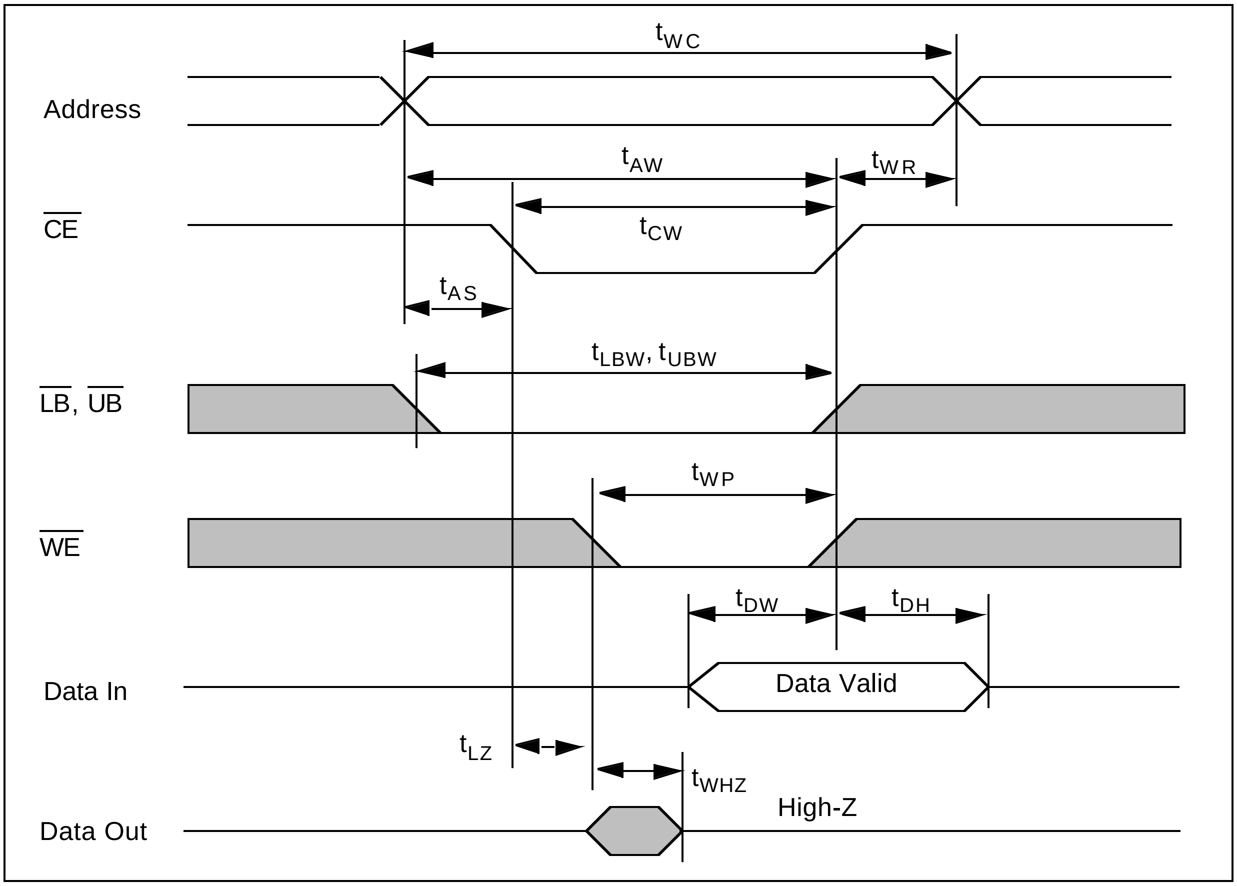
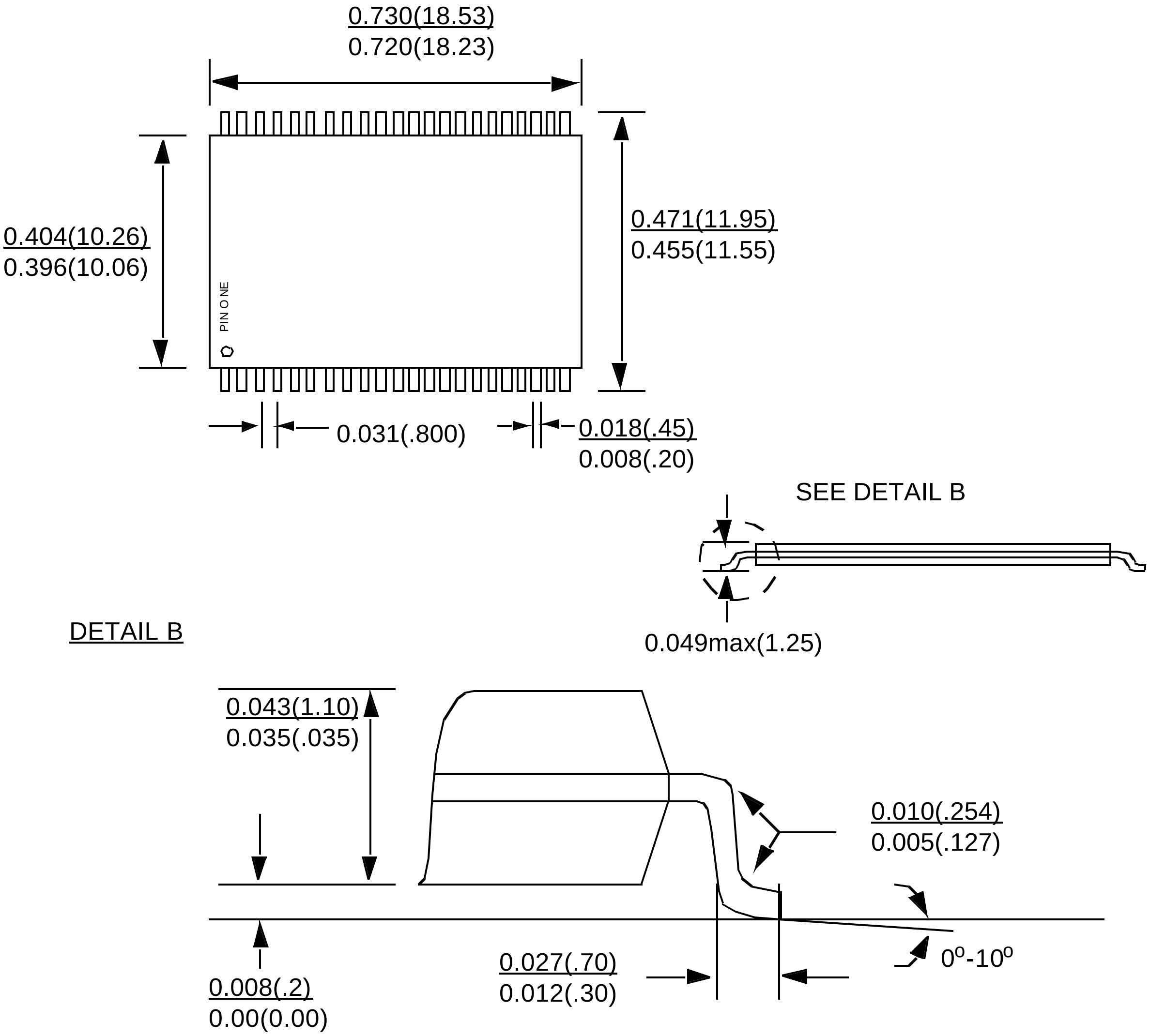
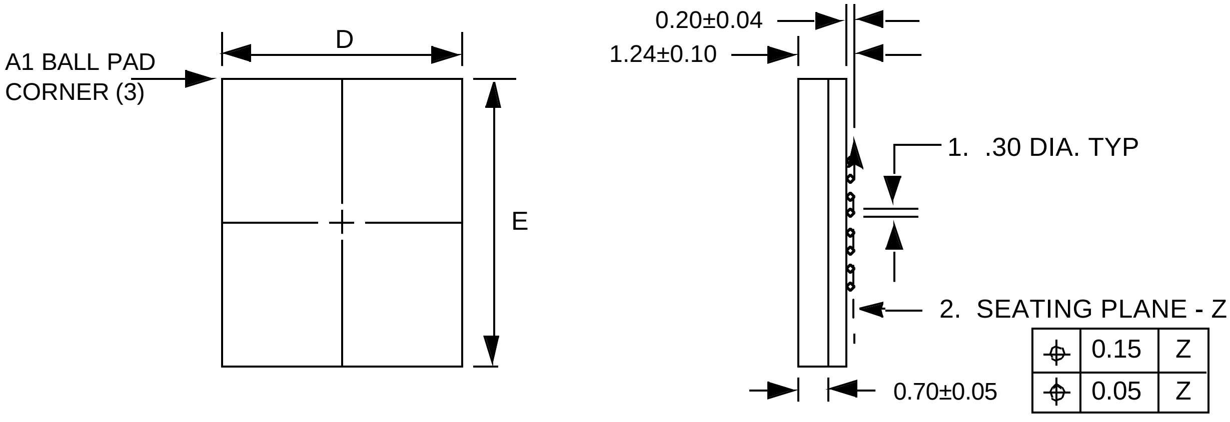


FIGURE 8: 44-LEAD TSOP PACKAGE (T44)

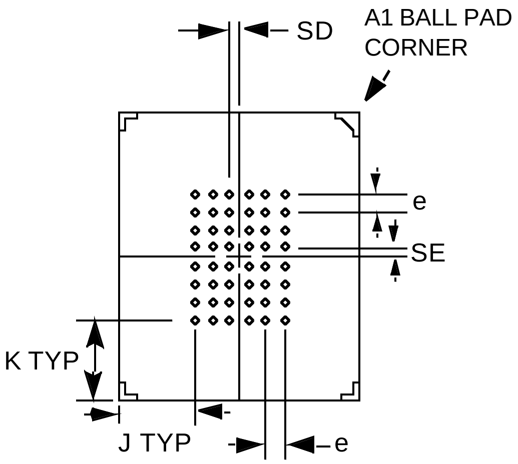


Note:
1. ALL DIMENSIONS IN INCHES (MILLIMETERS)
2. PACKAGE DIMENSIONS EXCLUDE MOLDING FLASH

FIGURE 9: BALL GRID ARRAY PACKAGING



TOP VIEW SIDE VIEW



BOTTOM VIEW

1. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER. PARALLEL TO PRIMARY Z.

2. PRIMARY DATUM Z AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

3. A1 BALL PAD CORNER I.D. TO BE MARKED BY INK.

TABLE 8: Dimensions (mm)

D	E	e = 0.75				BALL MATRIX TYPE
		SD	SE	J	K	
6	8	0.375	0.375	1.125	1.375	FULL

TABLE 9: Ordering Information

Part Number*	Package	Temperature Range	Voltage Range	Speed
EM256L16B	48 pin BGA	-40 to +85°C	2.3 to 3.6 V	70 ns @ 2.7 V
EM256L16T	44 pin TSOP	-40 to +85°C	2.3 to 3.6 V	70 ns @ 2.7 V

* This part number must appear on your order.

TABLE 10: Revision History

Revision	Date	Change Description
01	Jan 2001	Initial Preliminary Release
02	Mar 2001	Eliminated CE2 from BGA pinout, other minor errata
03	May 2001	Revised figure 8
04	June 2001	Revised table 8

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